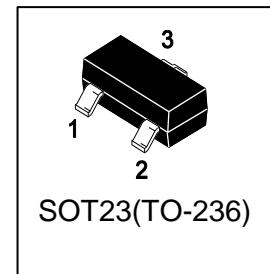


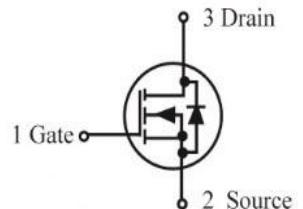
S-LN2308LT1G

60V N-Channel Enhancement-Mode MOSFET



1. FEATURES

- Exceptional on-resistance and maximum DC current capability.
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



2. APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch

3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
S-LN2308LT1G	N08	3000/Tape&Reel
S-LN2308LT3G	N08	10000/Tape&Reel

4. MAXIMUM RATINGS($T_a = 25^\circ\text{C}$)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		VDSS	60	V
Gate-Source Voltage		VGS	± 20	V
Continuous Drain Current	TA = 25°C	ID	2.6	A
	TA = 70°C		1.8	
Pulsed Drain Current		IDM	8	W
Maximum Power Dissipation	TA = 25°C	PD	0.7	
	TA = 70°C		0.45	
Junction and Storage temperature		TJ,Tstg	-55~+150	°C

5. THERMAL CHARACTERISTICS

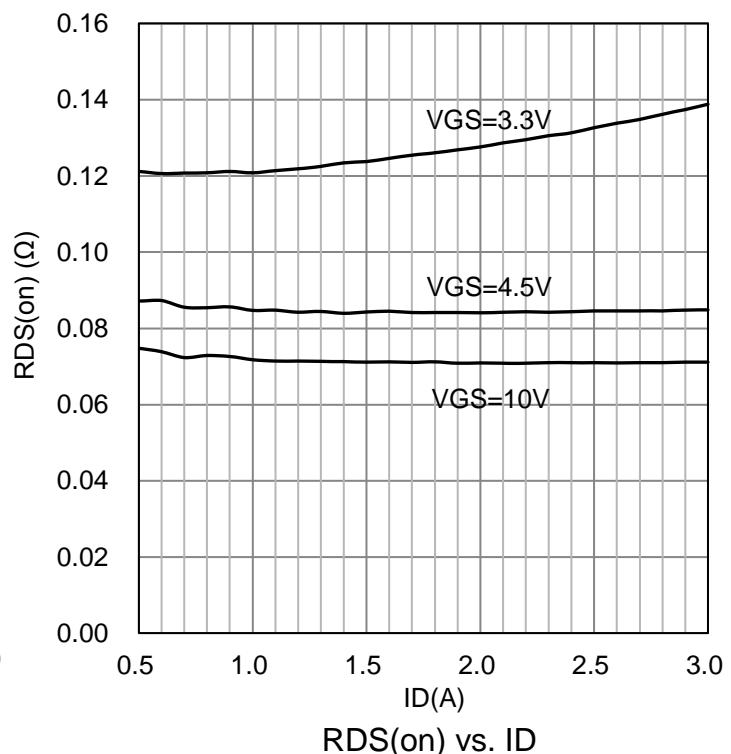
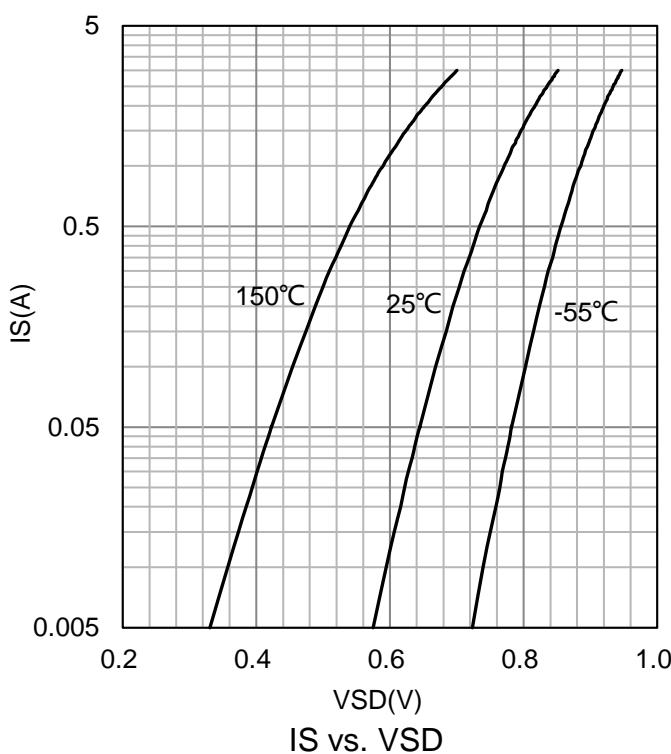
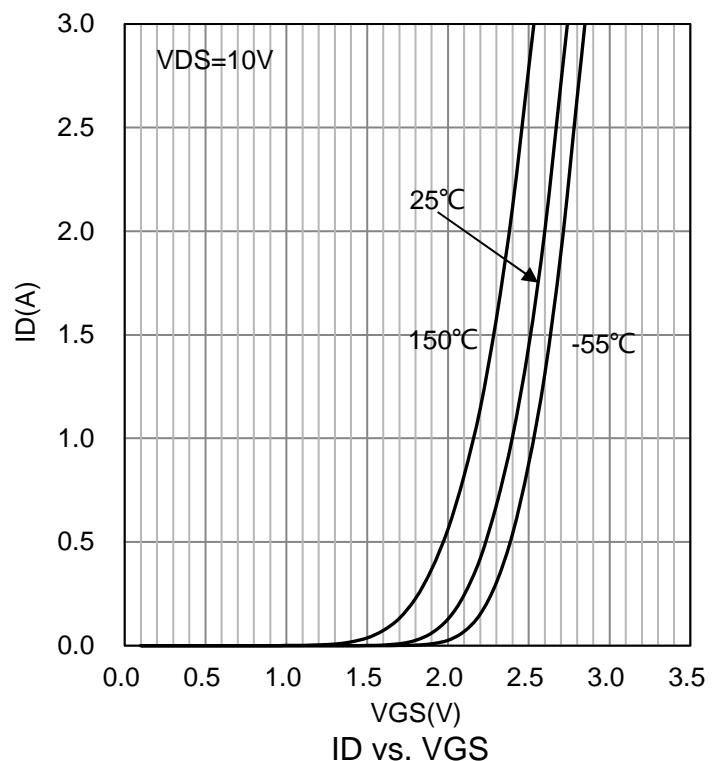
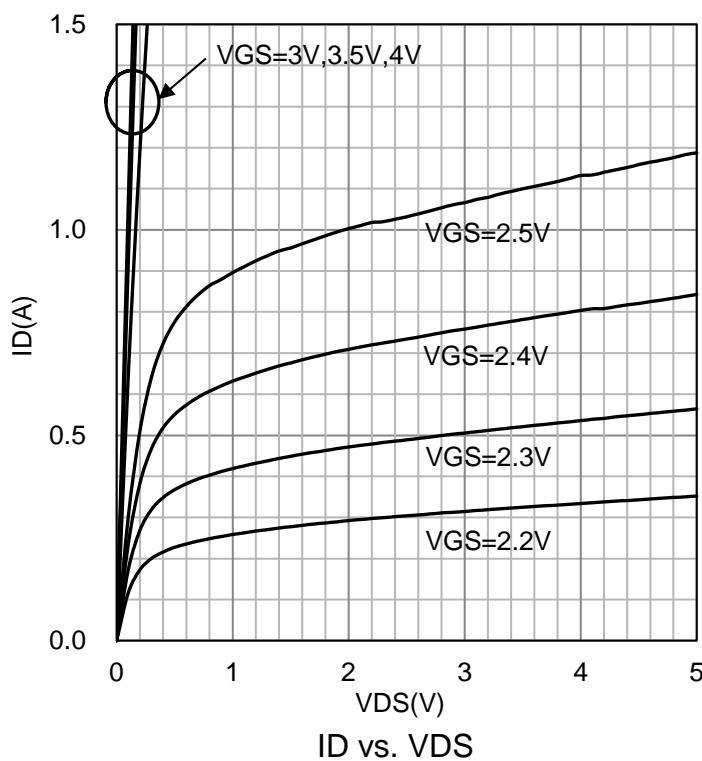
Parameter		Symbol	Limits	Unit
Maximum Junction-to-Ambient(Note 1)	T ≤ 10 sec	R _{θJA}	150	°C/W
	Steady State		175	
Thermal Resistance-Junction to Case		R _{θJC}	120	

1. Surface mounted on "1.5 x 1.5" FR4 board using 1 sq in pad, 2 oz Cu

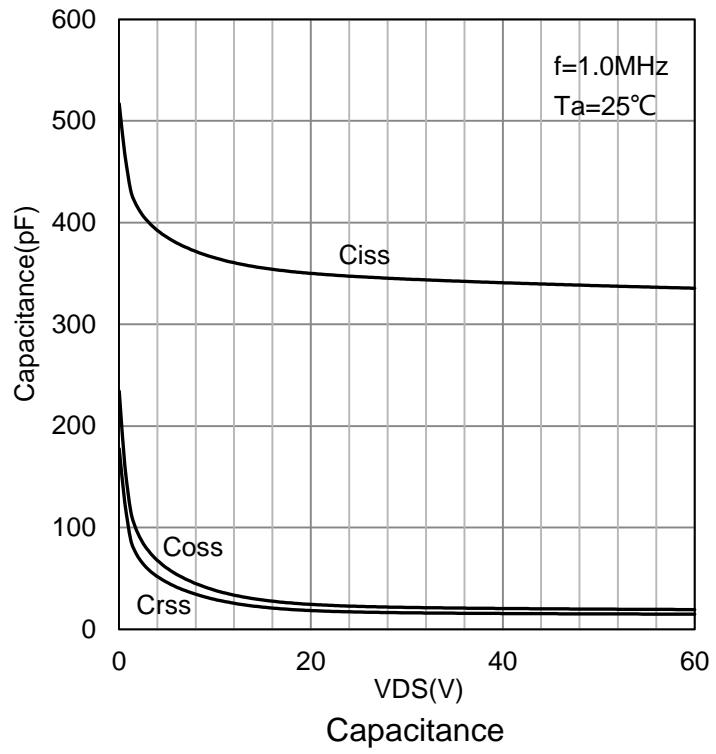
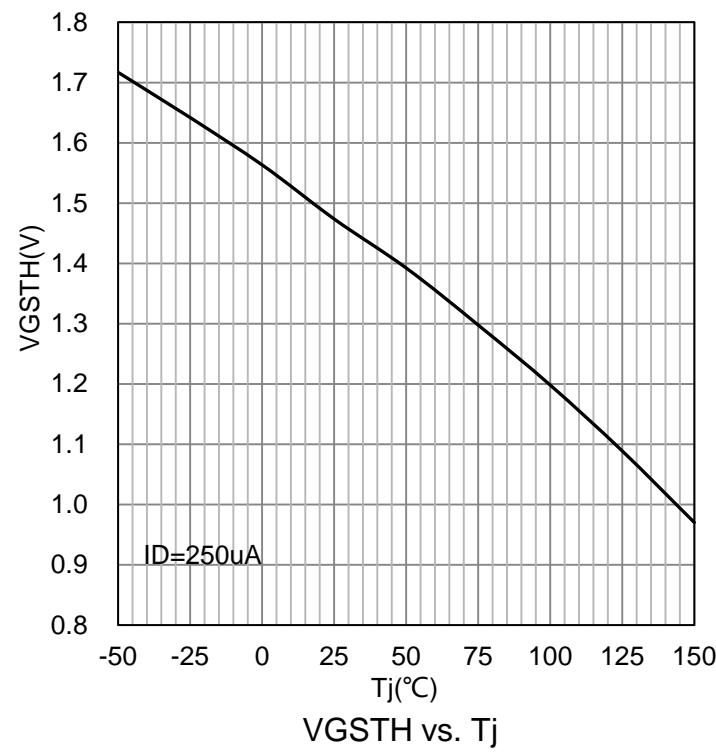
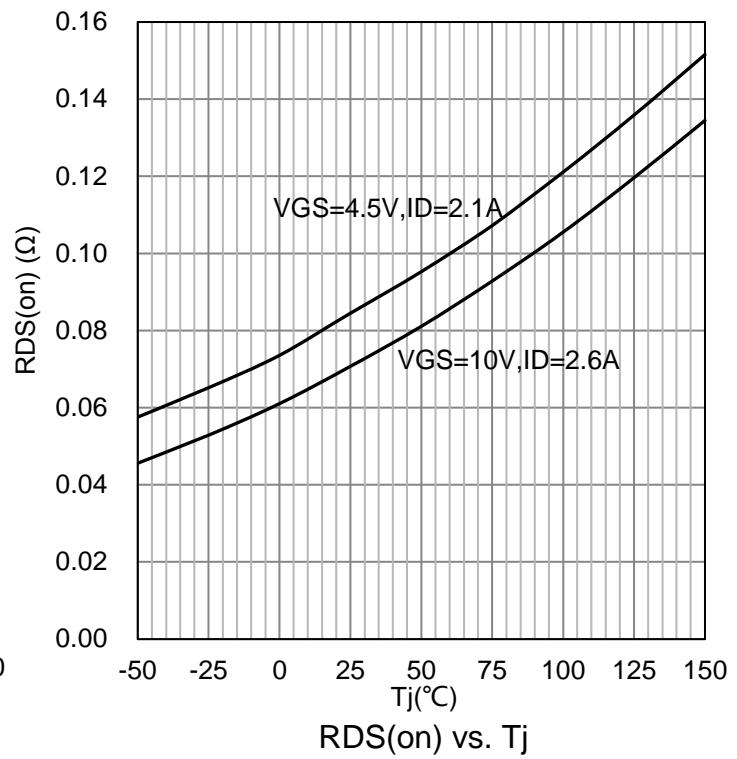
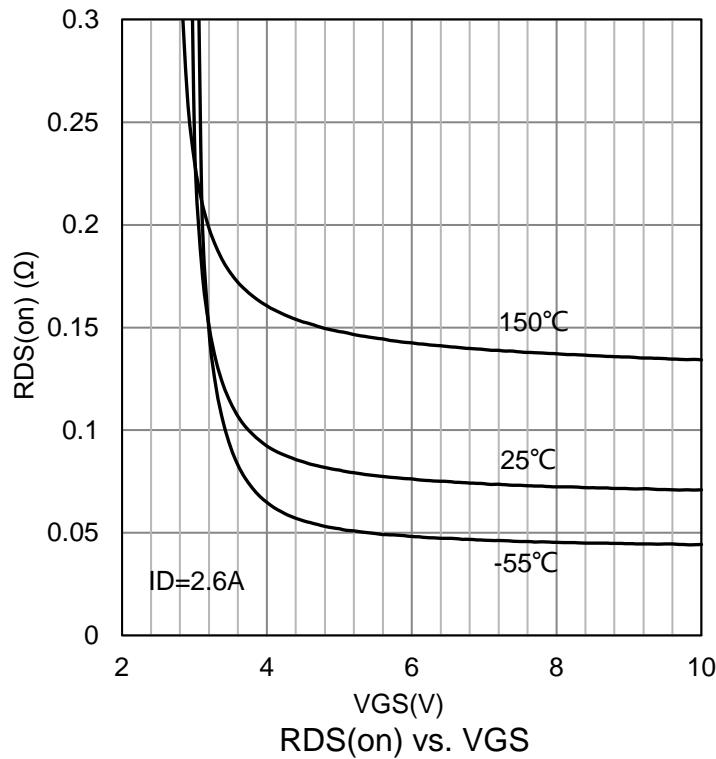
6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain–Source Breakdown Voltage (VGS = 0, ID = 250µA)	V(BR)DSS	60	-	-	V
Gate Threshold Voltage (VDS = VGS, ID = 250µA)	VGS(th)	1.0	-	3.0	V
Gate Body Leakage (VDS =0V, VGS =±20V)	IGSS	-	-	±100	nA
Zero Gate Voltage Drain Current (VDS =60V, VGS =0V)	IDSS	-	-	1	µA
Drain-Source On-Resistance (VGS =10V, ID = 2.6A) (VGS =4.5V, ID = 2.1A) (VGS =3.3V, ID = 1.8A)	RDS(on)	- - -	82 96 139	100 130 200	mΩ
Diode Forward Voltage (IS =1.0A, VGS =0V)	VSD	-	0.8	1.2	V
Dynamic					
Total Gate Charge(VGS=10V)	(VDS =30V, ID=2.6A)	Qg	-	6.4	-
Total Gate Charge(VGS=4.5V)		Qg	-	3.5	-
Gate-Source Charge		Qgs	-	0.9	-
Gate-Drain Charge		Qgd	-	1.8	-
Input capacitance	(VDS =30V, VGS =0V, f=1MHz)	Ciss	-	337	-
Output Capacitance		Coss	-	22	-
Reverse Transfer Capacitance		Crss	-	15.8	-
Turn-On Delay Time	(VDD =20V, RL =20Ω, ID =1A, VGEN =10V, RG =1Ω)	td(on)	-	3.9	-
Turn-On Rise Time		tr	-	6.9	-
Turn-Off Delay Time		td(off)	-	13.6	-
Turn-Off Fall Time		tf	-	2.1	-
Gate Resistance (VDS =0V, VGS =0V, f=1MHz)	Rg	-	0.7	1.1	Ω

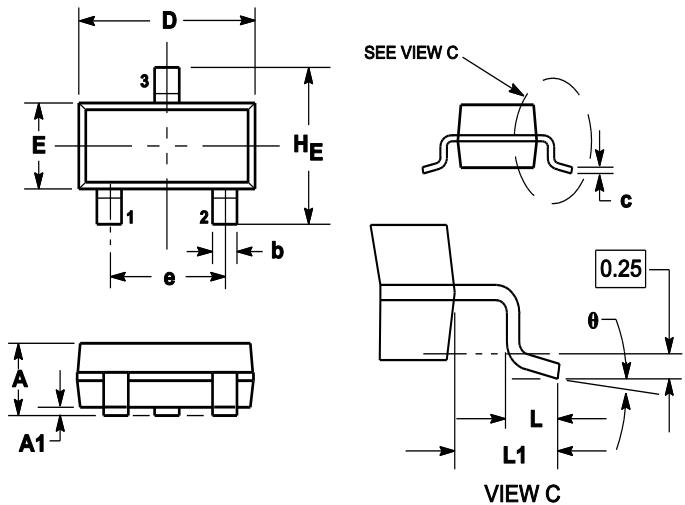
7.ELECTRICAL CHARACTERISTICS CURVES



7.ELECTRICAL CHARACTERISTICS CURVES (Con.)



8.OUTLINE AND DIMENSIONS

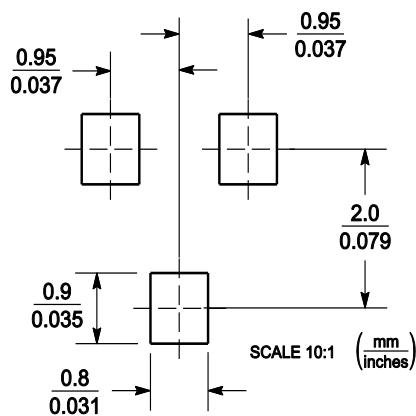


Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H _E	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

9.SOLDERING FOOTPRINT





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